

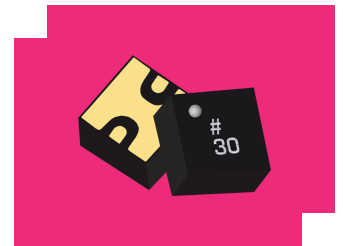
# ATN03-0070CSP1

## Chip Scale Package MMIC DC - 70 GHz 3dB Attenuator

### DEVICE OVERVIEW

#### General Description

The ATN03-0070CSP1 is a surface mount GaAs MMIC attenuator in a chip scale package (CSP). This attenuator is an ideal solution for attenuating a signal and can be used in a wide range of applications. The ATN03-0070CSP1 features a typical 3.2 dB attenuation with 0.1 dB attenuation flatness and 22 dB return loss across the DC-70 GHz bandwidth. The CSP allows for extreme miniaturization of SMT footprint while providing die-level performance. GaAs MMIC technology provides consistent unit-to-unit performance in a small, low-cost form factor. A 50-ohm match is maintained over the entire operating frequency range.



[Download s-parameters here](#)

#### Features

- 1.5 x 1.5 mm chip scale package
- 3.2 dB attenuation
- 0.1 dB attenuation flatness
- 22 dB return loss
- 1 W RF Power Handling
- This product embodies Marki Microwave's U.S. Pat. 11,869,858.

#### Applications

- 5G
- Test Equipment
- Precision Characterization
- Airborne Applications
- Amplitude Matching
- High Channel Count Systems

#### Functional Block Diagram



#### Part Ordering Options

Part Number	Description	Package	Green Status	Product Lifecycle	Export Classification
ATN03-0070CSP1	Chip Scale Package MMIC DC - 70 GHz 3dB Attenuator	CSP1	REACH RoHS	Released	EAR99
<u>EVB-ATN03-0070</u>	Evaluation Board, Chip Scale Package MMIC DC - 70 GHz 3dB Attenuator	EVB	REACH RoHS	Released	EAR99

## ATN03-0070CSP1

### Chip Scale Package MMIC DC - 70 GHz 3dB Attenuator

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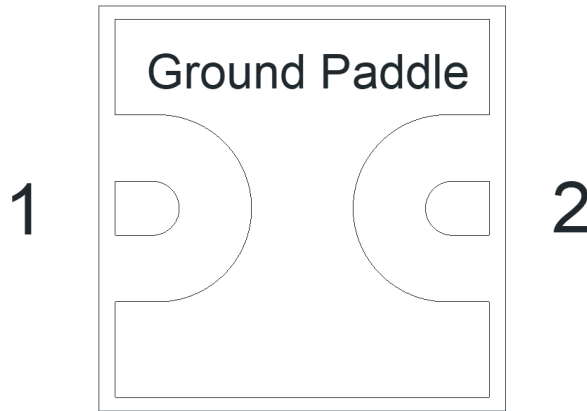
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#### Revision History

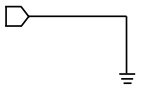
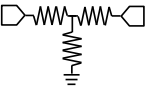
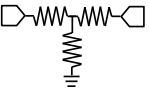
Revision Code	Revision Date	Comment
-	2024-10-31	Initial Release

### Port Configuration and Functions

#### Port Diagram



#### Port Functions

Port	Function	Description	DC Equivalent Circuit
Ground Paddle	Ground	CSP package ground path is provided through the ground paddle.	
Pin 1	Input/Output	Pin 1 and Pin 2 are DC connected to each other and ground through a T-network of resistors.	
Pin 2	Input/Output	Pin 1 and Pin 2 are DC connected to each other and ground through a T-network of resistors.	

## Specifications

### Absolute Maximum Ratings

The Absolute Maximum Ratings indicate limits beyond which damage may occur to the device. If these limits are exceeded, the device may be inoperable or have a reduced lifetime.

Parameter	Maximum Rating	Unit
Maximum Operating Temperature	100	°C
Maximum Storage Temperature	125	°C
Minimum Operating Temperature	-55	°C
Minimum Storage Temperature	-65	°C
RF Power Handling	1	W

### Package Information

Parameter	Details	Rating
ESD	250 to < 500 Volts	HBM Class 1A
Dimensions	-	1.5 x 1.5 mm
Moisture Sensitivity Level	-	MSL 3

#### Electrical Specifications

The electrical specifications apply at TA=+25°C in a 50Ω system. Typical data shown is for the attenuator in a CSP1 package with a sine wave input applied to port 1.

Parameter	Test Conditions	Minimum Frequency (GHz)	Maximum Frequency (GHz)	Min	Typ	Max	Unit
Attenuation	Configuration A, Temp = 25°C	0	70	-	3.2	-	dB
Return Loss	Configuration A, Temp = 25°C	0	70	-	22	-	dB
Attenuation Flatness <sup>1</sup>	Configuration A, Temp = 25°C	0	70	-	0.7	-	dB
Impedance	-	0	70	-	50	-	Ω

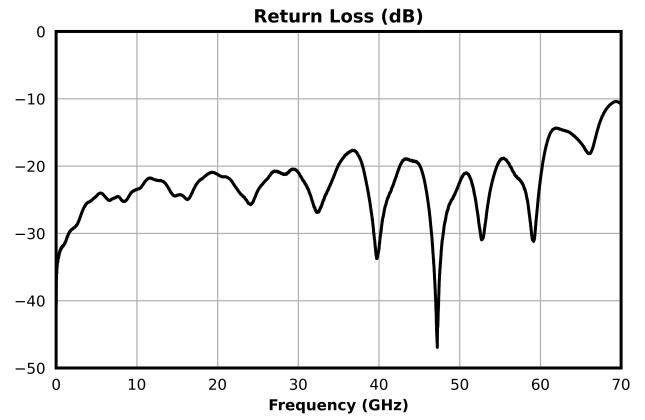
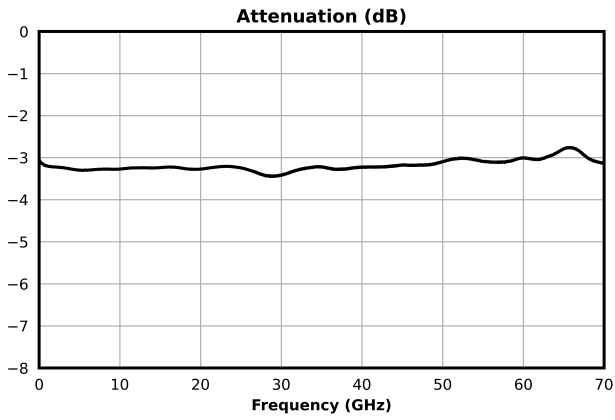
<sup>[1]</sup> Attenuation Flatness = Max(Insertion Loss) - Min(Insertion Loss)

## ATN03-0070CSP1

Chip Scale Package MMIC DC - 70 GHz 3dB  
Attenuator

### Typical Performance Plots

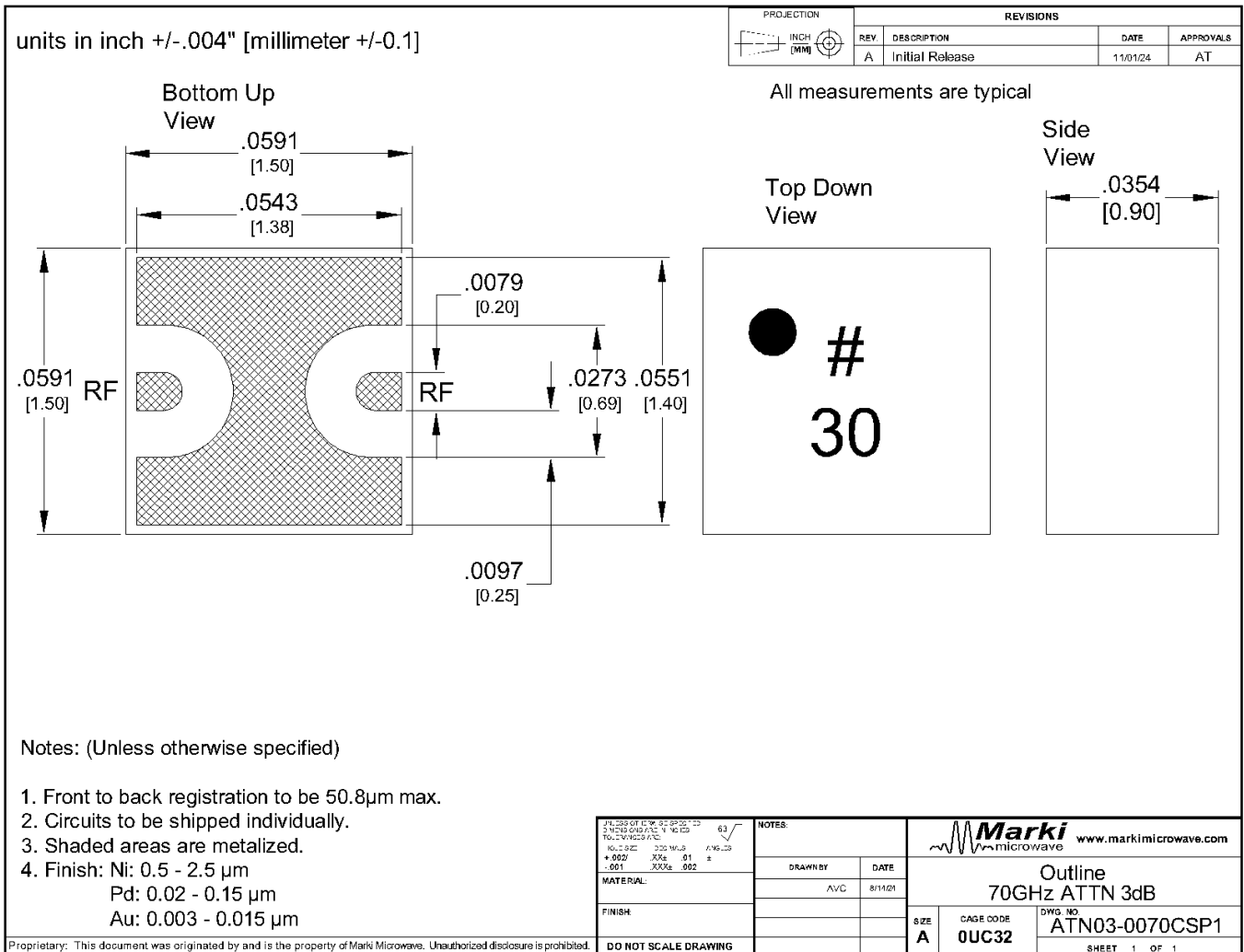
Electrical performance data is de-embedded to the CSP package ports.



### Mechanical Data

### Outline Drawing

Download : [Outline 2D Drawing](#) | [Outline 3D Drawing](#) | [Outline 3D STP](#)



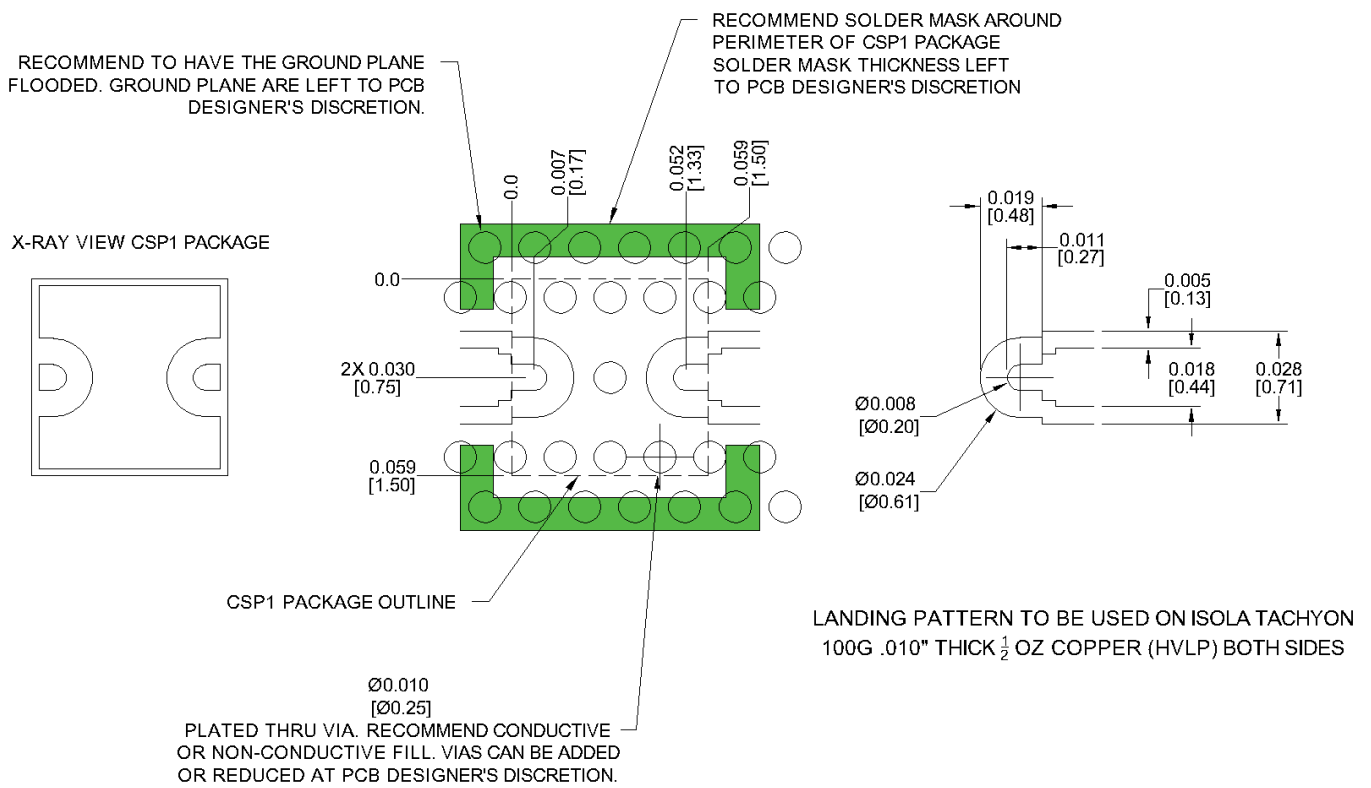
## ATN03-0070CSP1

### Chip Scale Package MMIC DC - 70 GHz 3dB Attenuator

#### Footprint Image

Download : [Footprint Drawing](#)

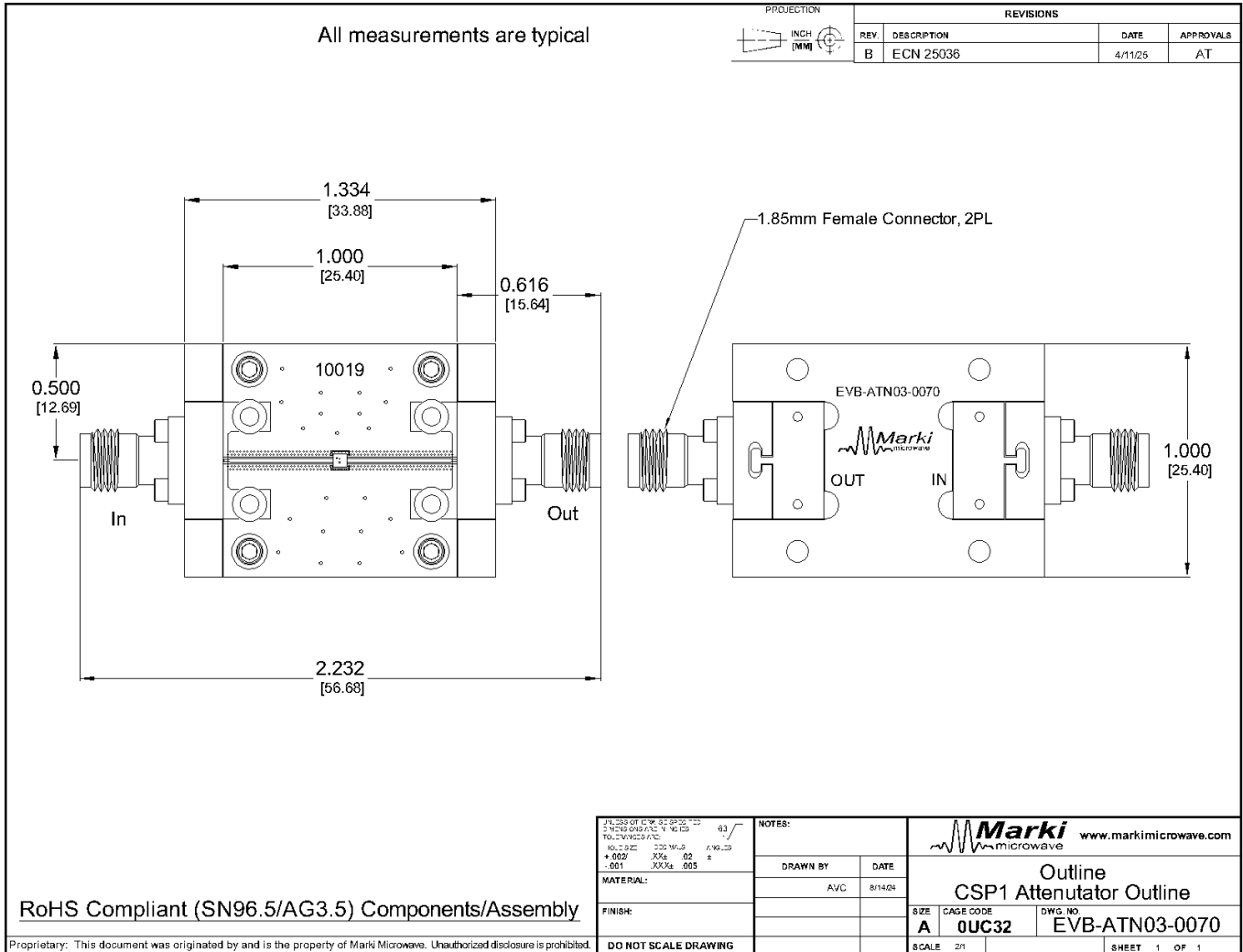
\*PRIMARY DIMENSIONS ARE IN INCHES



# ATN03-0070CSP1

Chip Scale Package MMIC DC - 70 GHz 3dB Attenuator

## Evaluation Board - Outline Drawing



## ATN03-0070CSP1

### Chip Scale Package MMIC DC - 70 GHz 3dB Attenuator

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